## Advance Information

# Quad Analog Switch/ Multiplexer/Demultiplexer

## **High-Performance Silicon-Gate CMOS**

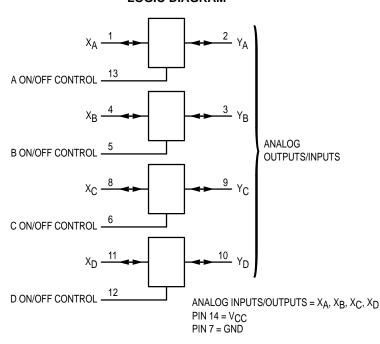
The MC74LVX4066 utilizes silicon–gate CMOS technology to achieve fast propagation delays, low ON resistances, and low OFF–channel leakage current. This bilateral switch/multiplexer/demultiplexer controls analog and digital voltages that may vary across the full power–supply range (from  $V_{CC}$  to GND).

The LVX4066 is identical in pinout to the metal–gate CMOS MC14066 and the high–speed CMOS HC4066A. Each device has four independent switches. The device has been designed so that the ON resistances (R<sub>ON</sub>) are much more linear over input voltage than R<sub>ON</sub> of metal–gate CMOS analog switches.

The ON/OFF control inputs are compatible with standard CMOS outputs; with pull-up resistors, they are compatible with LSTTL outputs.

- Fast Switching and Propagation Speeds
- High ON/OFF Output Voltage Ratio
- Low Crosstalk Between Switches
- Diode Protection on All Inputs/Outputs
- Wide Power–Supply Voltage Range (VCC GND) = 2.0 to 6.0 Volts
- Analog Input Voltage Range (V<sub>CC</sub> GND) = 2.0 to 6.0 Volts
- Improved Linearity and Lower ON Resistance over Input Voltage than the MC14016 or MC14066
- Low Noise
- Chip Complexity: 44 FETs or 11 Equivalent Gates

## LOGIC DIAGRAM



## MC74LVX4066



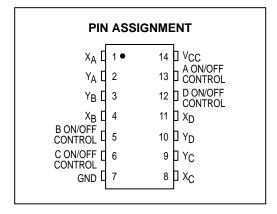
**D SUFFIX** 14–LEAD SOIC PACKAGE CASE 751A–03



**DT SUFFIX** 14-LEAD TSSOP PACKAGE CASE 948G-01

#### **ORDERING INFORMATION**

MC74LVXxxxxD SOIC MC74LVXxxxxDT TSSOP



<b>FUNCTION TABLE</b>			
On/Off Control Input	State of Analog Switch		
L	Off		
Н	On		

This document contains information on a new product. Specifications and information herein are subject to change without notice.



#### **MAXIMUM RATINGS\***

Symbol	Parameter	Value	Unit
VCC	Positive DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V
VIS	Analog Input Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> + 0.5	V
V <sub>in</sub>	Digital Input Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> + 0.5	V
l <sub>in</sub>	DC Current Into or Out of ON/OFF Control Pins	± 20	mA
I <sub>S</sub>	DC Current Into or Out of Switch Pins	± 20	mA
PD	Power Dissipation in Still Air, SOIC Package† TSSOP Package†	500 450	mW
T <sub>stg</sub>	Storage Temperature	- 65 to + 150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C

<sup>\*</sup> Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
Vcc	Positive DC Supply Voltage (Referenced to GND)	2.0	6.0	V
VIS	Analog Input Voltage (Referenced to GND)	GND	Vcc	V
V <sub>in</sub>	Digital Input Voltage (Referenced to GND)	GND	Vcc	V
V <sub>IO</sub> *	Static or Dynamic Voltage Across Switch	_	1.2	V
T <sub>A</sub>	Operating Temperature, All Package Types	- 55	+ 85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time, ON/OFF Control Inputs (Figure 10) $ \begin{array}{c} \text{V}_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V} \\ \text{V}_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V} \end{array} $	0 0	100 20	ns/V

<sup>\*</sup> For voltage drops across the switch greater than 1.2 V (switch on), excessive V<sub>CC</sub> current may be drawn; i.e., the current out of the switch may contain both VCC and switch input components. The reliability of the device will be unaffected unless the Maximum Ratings are exceeded.

## DC ELECTRICAL CHARACTERISTIC Digital Section (Voltages Referenced to GND)

				Guaranteed Limit		mit	
Symbol	Parameter	Test Conditions	V <sub>CC</sub>	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
VIH	Minimum High-Level Voltage ON/OFF Control Inputs (Note 1)	R <sub>on</sub> = Per Spec	2.0 3.0 4.5 5.5	1.5 2.1 3.15 3.85	1.5 2.1 3.15 3.85	1.5 2.1 3.15 3.85	V
VIL	Maximum Low–Level Voltage ON/OFF Control Inputs (Note 1)	R <sub>on</sub> = Per Spec	2.0 3.0 4.5 5.5	0.5 0.9 1.35 1.65	0.5 0.9 1.35 1.65	0.5 0.9 1.35 1.65	V
l <sub>in</sub>	Maximum Input Leakage Current ON/OFF Control Inputs	$V_{in} = V_{CC}$ or GND	5.5V	± 0.1	± 1.0	± 1.0	μА
lcc	Maximum Quiescent Supply Current (per Package)	V <sub>in</sub> = V <sub>CC</sub> or GND V <sub>IO</sub> = 0 V	5.5	4.0	40	160	μΑ

<sup>1.</sup> Specifications are for design target only. Not final specification limits.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated

voltages to this high-impedance circuit. For proper operation, Vin and Vout should be constrained to the range GND  $\leq$  (V<sub>in</sub> or V<sub>out</sub>)  $\leq$  V<sub>CC</sub>. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or VCC). Unused outputs must be left open. I/O pins must be connected to a properly terminated line or bus.

<sup>†</sup>Derating — SOIC Package: - 7 mW/°C from 65° to 125°C TSSOP Package: - 6.1 mW/°C from 65° to 125°C

## DC ELECTRICAL CHARACTERISTICS Analog Section (Voltages Referenced to GND)

				Guaranteed Limit			
Symbol	Parameter	Test Conditions	V <sub>CC</sub>	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
R <sub>on</sub>	Maximum "ON" Resistance	$V_{\text{in}} = V_{\text{IH}}$ $V_{\text{IS}} = V_{\text{CC}}$ to GND $ I_{\text{S}}  \le 10$ mA (Figures 1, 2)	2.0† 3.0 4.5 5.5	— 30 25 20	— 35 30 25	— 40 35 30	Ω
		$V_{\text{IN}} = V_{\text{IH}}$ $V_{\text{IS}} = V_{\text{CC}}$ or GND (Endpoints) $ I_{\text{S}}  \le 10 \text{ mA}$ (Figures 1, 2)	2.0 3.0 4.5 5.5	— 20 15 15	— 25 20 20	— 30 25 25	
ΔR <sub>on</sub>	Maximum Difference in "ON" Resistance Between Any Two Channels in the Same Package	$V_{IN} = V_{IH}$ $V_{IS} = 1/2 (V_{CC} - GND)$ $I_{S} \le 2.0 \text{ mA}$	3.0 4.5 5.5	15 8.0 4.0	20 12 7.0	25 15 10	Ω
l <sub>off</sub>	Maximum Off-Channel Leakage Current, Any One Channel	V <sub>in</sub> = V <sub>IL</sub> V <sub>IO</sub> = V <sub>CC</sub> or GND Switch Off (Figure 3)	5.5	0.1	0.5	1.0	μА
l <sub>on</sub>	Maximum On-Channel Leakage Current, Any One Channel	V <sub>in</sub> = V <sub>IH</sub> V <sub>IS</sub> = V <sub>CC</sub> or GND (Figure 4)	5.5	0.1	0.5	1.0	μА

<sup>†</sup>At supply voltage (V<sub>CC</sub>) approaching 2 V the analog switch–on resistance becomes extremely non–linear. Therefore, for low–voltage operation, it is recommended that these devices only be used to control digital signals (See Figure 1a).

## AC ELECTRICAL CHARACTERISTICS ( $C_L = 50 \text{ pF}$ , ON/OFF Control Inputs: $t_f = t_f = 6 \text{ ns}$ )

			Gu	Guaranteed Limit		
Symbol	Parameter	v <sub>CC</sub>	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Analog Input to Analog Output (Figures 8 and 9)	2.0 3.0 4.5 5.5	4.0 3.0 1.0 1.0	6.0 5.0 2.0 2.0	8.0 6.0 2.0 2.0	ns
tPLZ, tPHZ	Maximum Propagation Delay, ON/OFF Control to Analog Output (Figures 10 and 11)	2.0 3.0 4.5 5.5	30 20 15 15	35 25 18 18	40 30 22 20	ns
tPZL, tPZH	Maximum Propagation Delay, ON/OFF Control to Analog Output (Figures 10 and 1 1)	2.0 3.0 4.5 5.5	20 12 8.0 8.0	25 14 10 10	30 15 12 12	ns
С	Maximum Capacitance ON/OFF Control Input Control Input = GND Analog I/O Feedthrough	_ _ _	10 35 1.0	10 35 1.0	10 35 1.0	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
C <sub>PD</sub>	Power Dissipation Capacitance (Per Switch) (Figure 13)*	15	pF

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<sup>\*</sup> Used to determine the no–load dynamic power consumption:  $P_D = C_{PD} \ V_{CC}^2 f + I_{CC} \ V_{CC}$ .

## ADDITIONAL APPLICATION CHARACTERISTICS (Voltages Referenced to GND Unless Noted)

Symbol	Parameter	Test Conditions	v <sub>CC</sub>	Limit* 25°C	Unit
BW	Maximum On–Channel Bandwidth or Minimum Frequency Response (Figure 5)	$\begin{aligned} f_{in} &= 1 \text{ MHz Sine Wave} \\ &\text{Adjust } f_{in} \text{ Voltage to Obtain 0 dBm at V}_{OS} \\ &\text{Increase } f_{in} \text{ Frequency Until dB Meter Reads} - 3 \text{ dB} \\ &\text{R}_{L} &= 50 \Omega, \text{ C}_{L} = 10 \text{ pF} \end{aligned}$	4.5 5.5	150 160	MHz
_	Off–Channel Feedthrough Isolation (Figure 6)	$  f_{\text{in}} \equiv \text{Sine Wave} \\                                   $	4.5 5.5	- 50 - 50	dB
		$f_{in} = 1.0 \text{ MHz}, R_L = 50 \Omega, C_L = 10 \text{ pF}$	4.5 5.5	- 40 - 40	
_	Feedthrough Noise, Control to Switch (Figure 7)	$V_{in} \leq$ 1 MHz Square Wave ( $t_{\Gamma} = t_{f} = 6$ ns) Adjust R <sub>L</sub> at Setup so that I <sub>S</sub> = 0 A R <sub>L</sub> = 600 $\Omega$ , C <sub>L</sub> = 50 pF	4.5 5.5	100 200	mVpp
		$R_L$ = 10 kΩ, $C_L$ = 10 pF	4.5 5.5	50 100	
_	Crosstalk Between Any Two Switches (Figure 12)	$ \begin{aligned} f_{\text{in}} &\equiv \text{Sine Wave} \\ \text{Adjust } f_{\text{in}} &\text{ Voltage to Obtain 0 dBm at V}_{\text{IS}} \\ f_{\text{in}} &= 10 \text{ kHz}, \text{ R}_{\text{L}} = 600 \ \Omega, \text{ C}_{\text{L}} = 50 \text{ pF} \end{aligned} $	4.5 5.5	- 70 - 70	dB
		$f_{in} = 1.0 \text{ MHz}, R_L = 50 \Omega, C_L = 10 \text{ pF}$	4.5 5.5	- 80 - 80	
THD	Total Harmonic Distortion (Figure 14)	$f_{\text{in}} = 1 \text{ kHz},  \text{R}_{\text{L}} = 10 \text{ k}\Omega,  \text{C}_{\text{L}} = 50 \text{ pF}$ $\text{THD} = \text{THD}_{\text{Measured}} - \text{THD}_{\text{Source}}$ $\text{V}_{\text{IS}} = 4.0 \text{ Vpp sine wave}$ $\text{V}_{\text{IS}} = 5.0 \text{ Vpp sine wave}$	4.5 5.5	0.10 0.06	%

<sup>\*</sup> Guaranteed limits not tested. Determined by design and verified by qualification.

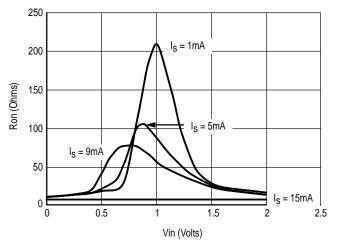


Figure 1a. Typical On Resistance,  $V_{CC}$  = 2.0 V, T = 25°C

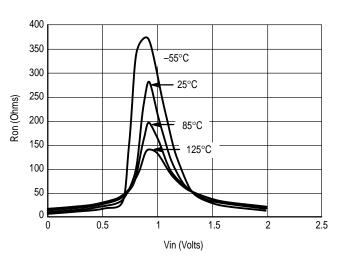


Figure 1b. Typical On Resistance, V<sub>CC</sub> = 2.0 V

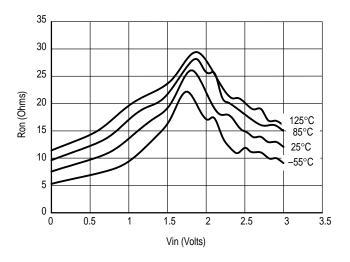


Figure 1c. Typical On Resistance, V<sub>CC</sub> = 3.0 V

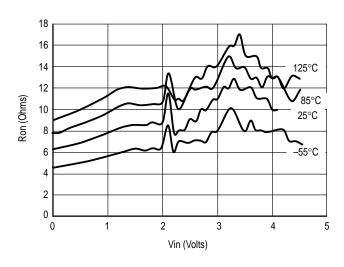


Figure 1d. Typical On Resistance, V<sub>CC</sub> = 4.5 V

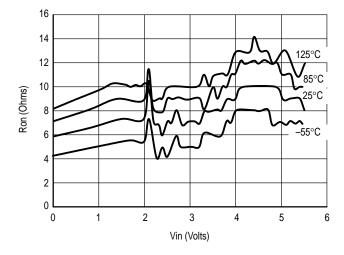


Figure 1e. Typical On Resistance, V<sub>CC</sub> = 5.5 V

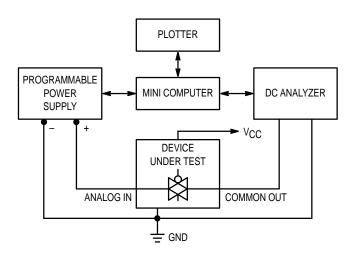


Figure 2. On Resistance Test Set-Up

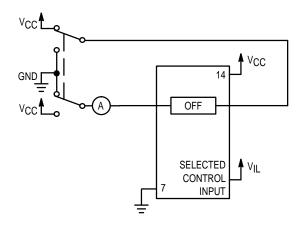


Figure 3. Maximum Off Channel Leakage Current, Any One Channel, Test Set-Up

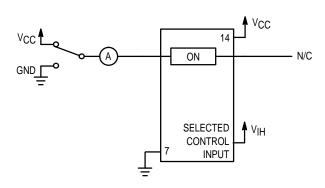
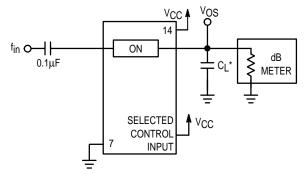
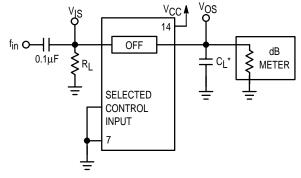


Figure 4. Maximum On Channel Leakage Current, Test Set-Up



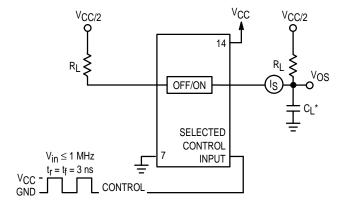
\*Includes all probe and jig capacitance.

Figure 5. Maximum On-Channel Bandwidth
Test Set-Up



\*Includes all probe and jig capacitance.

Figure 6. Off-Channel Feedthrough Isolation, Test Set-Up



\*Includes all probe and jig capacitance.

Figure 7. Feedthrough Noise, ON/OFF Control to Analog Out, Test Set-Up

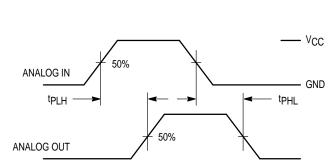
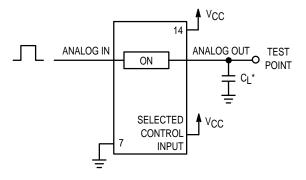
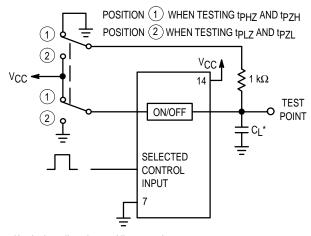


Figure 8. Propagation Delays, Analog In to Analog Out



<sup>\*</sup>Includes all probe and jig capacitance.

Figure 9. Propagation Delay Test Set-Up



<sup>\*</sup>Includes all probe and jig capacitance.

Figure 11. Propagation Delay Test Set-Up

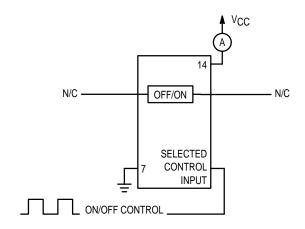


Figure 13. Power Dissipation Capacitance
Test Set-Up

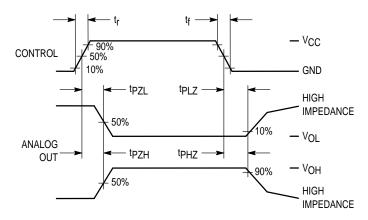
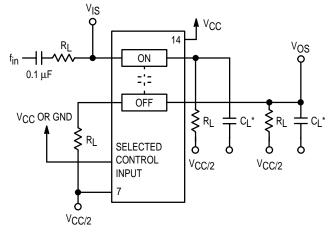
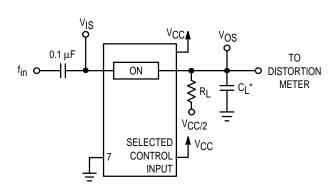


Figure 10. Propagation Delay, ON/OFF Control to Analog Out



\*Includes all probe and jig capacitance.

Figure 12. Crosstalk Between Any Two Switches, Test Set-Up



\*Includes all probe and jig capacitance.

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Figure 14. Total Harmonic Distortion, Test Set-Up

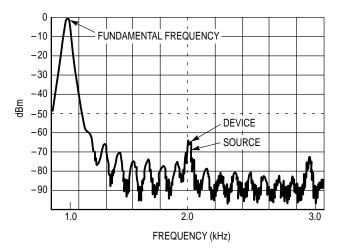


Figure 15. Plot, Harmonic Distortion

#### APPLICATION INFORMATION

The ON/OFF Control pins should be at V<sub>CC</sub> or GND logic levels, V<sub>CC</sub> being recognized as logic high and GND being recognized as a logic low. Unused analog inputs/outputs may be left floating (not connected). However, it is advisable to tie unused analog inputs and outputs to V<sub>CC</sub> or GND through a low value resistor. This minimizes crosstalk and feedthrough noise that may be picked–up by the unused I/O pins.

The maximum analog voltage swings are determined by the supply voltages V<sub>CC</sub> and GND. The positive peak analog voltage should not exceed V<sub>CC</sub>. Similarly, the negative peak

analog voltage should not go below GND. In the example below, the difference between  $V_{\hbox{CC}}$  and GND is six volts. Therefore, using the configuration in Figure 16, a maximum analog signal of six volts peak–to–peak can be controlled.

When voltage transients above V<sub>CC</sub> and/or below GND are anticipated on the analog channels, external diodes (Dx) are recommended as shown in Figure 17. These diodes should be small signal, fast turn—on types able to absorb the maximum anticipated current surges during clipping. An alternate method would be to replace the Dx diodes with MO•sorbs (Motorola high current surge protectors). MO•sorbs are fast turn—on devices ideally suited for precise DC protection with no inherent wear out mechanism.

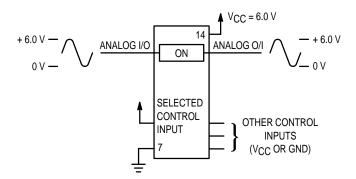


Figure 16. 6.0 V Application

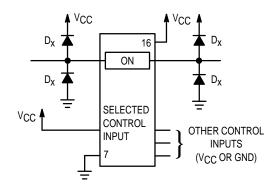


Figure 17. Transient Suppressor Application

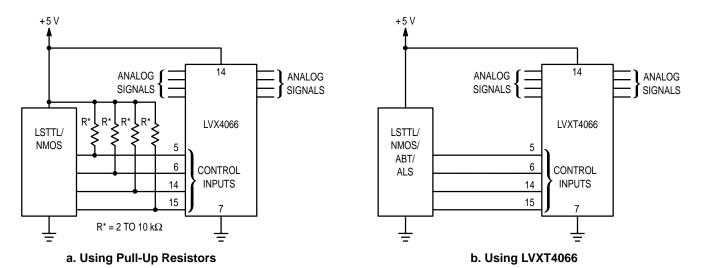


Figure 18. LSTTL/NMOS to CMOS Interface

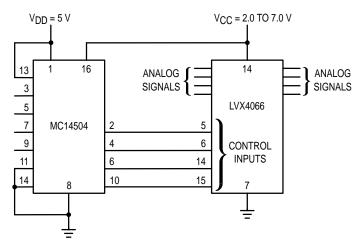


Figure 19. TTL/NMOS-to-CMOS Level Converter Analog Signal Peak-to-Peak Greater than 5 V

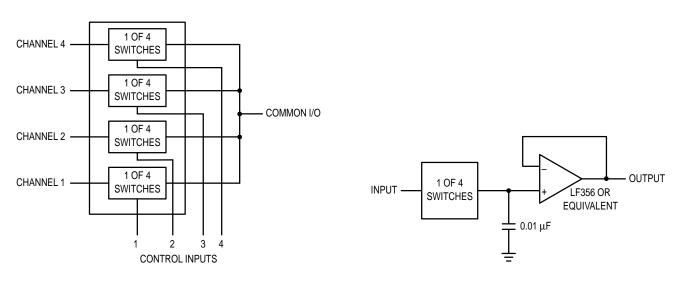
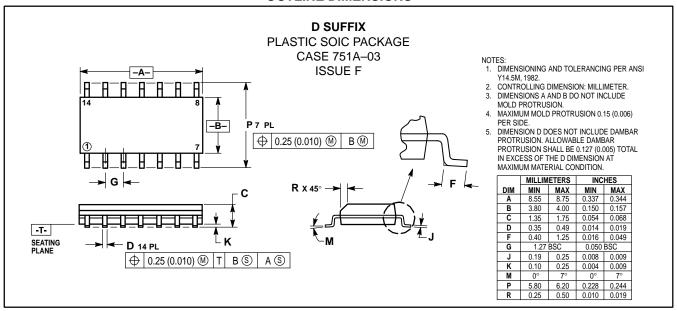


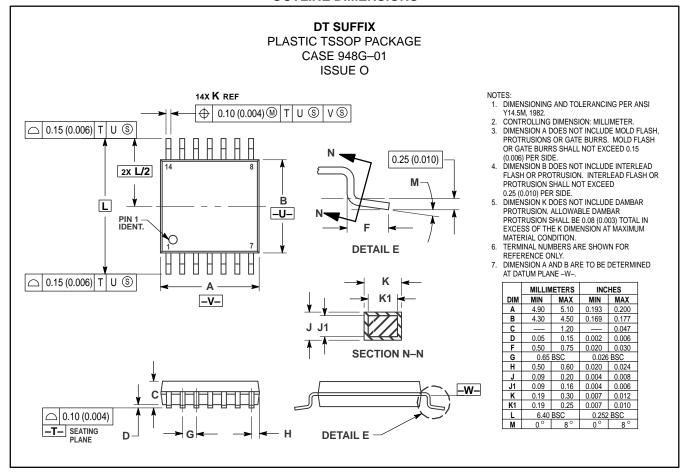
Figure 20. 4-Input Multiplexer

Figure 21. Sample/Hold Amplifier

### **OUTLINE DIMENSIONS**



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